

## **MATERIAL DATA FORM**

Manufacturer contact Information					
Contact Name	Compliance Coordinator				
Tel. No.	+1 (805) 377-3648				
E-mail address	Compliance@diodes.com				

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
DDZ3V6BSF – DDZ20BSF	0.005	Die,Zener	Doped silicon	TBD	0.0575	1.07%	10700
Customer's Partnumber.		SOD-323F leadframe	EFTEC-64T	TBD	1.3903	25.87%	258720
			Die attached pad plating	37507916	0.0505	0.94%	9396
		Bonding wire	Gold	3399000	0.0119	0.22%	2211
		Molding compound	KTMC-1050G	89310110	3.7094	69.03%	690291
		Tin solder	Pure Tin	37508652	0.1541	2.87%	28681

Total (mg) 5.374



## MATERIAL DATA FORM DETAIL

	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight
DDZ3V6BSF – DDZ20BSF	0.005	Die,Zener	Doped silicon	Si	7440-21-3	0.0575	100.00%	1000000	10700
Customer's Partnumber.				Cu	7440-50-8	1.3800	99.26%	992600	256806
		SOD-323F leadframe	EFTEC-64T	Cr(not Cr 6+)	7440-47-3	0.0038	0.27%	2700	699
				Sn	7440-31-5	0.0035	0.25%	2500	647
				Zn	7440-66-6	0.0031	0.22%	2200	569
			Pure silver	Ag	7440-22-4	0.0505	100.00%	1000000	9396
		Bonding wire	1.0mil	Au	7440-57-5	0.0119	100.00%	1000000	2211
				SiO2	60676-86-0	2.5595	69.00%	690000	476301
				Epoxy Resin	29690-82-2	0.5193	14.00%	140000	96641
		Molding compound	KTMC-1050G	Phenol Resin	9003-35-4	0.2597	7.00%	70000	48320
		Wording compound	K1100-10300	Mg(OH)2	1309-42-8	0.2967	8.00%	80000	55223
				С	1333-86-4	0.0074	0.20%	2000	1381
				others (wax, cata	al	0.0668	1.80%	18000	12425
		Tin solder	Pure Tin	Sn	7440-31-5	0.1541	100.00%	1000000	28681

Total (mg) 5.374

## MATERIALS DISCLOSURE DISCLAIMER

- 1. The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"
- 2. Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.
- 3. These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.

## This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELVII and RoHS and reported above:

- 1. Antimony compounds
- 2. Asbestos
- 3. Azo compounds
- 4. Cadmium and cadmium compounds
- 5. Certain Shortchain Chlorinated Paraffins
- 6. Chlorinated organic compounds
- 7. Halogens
- 8. Hexavalent chromium compounds
- 9. Lead and lead compounds
- 10. Mercury and mercury compounds
- 11. Organic tin compounds

- 12. Ozone Depleting Substances Class I (CFCs, HBFCs, etc.)
- 13. Ozone Depleting Substances Class II (HCFCs)
- 14. Perfluorooctane Sulphonate (PFOS) or related compounds
- 15. Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
- 16. Polychlorinated Biphenyls (PCBs)
- 17. Polychlorinated Naphthalenes (>3 chlorine atoms)
- 18. Radioactive Substances
- 19. Tributyl Tin (TBT) and Triphenyl Tin (TPT)
- 20. Tributyl Tin Oxide (TBTO)

This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:				
1. Anthracene	9. Bis (2-ethyl(hexyl)phthalate) (DEHP)			
2. 4,4'- Diaminodiphenylmethane	10. Hexabromocyclododecane (HBCDD)			
3. Dibutyl phthalate (DBP)	11. Bis(tributyltin)oxide (TBTO)			
4. Cyclododecane	12. Lead hydrogen arsenate			
5. Cobalt dichloride	13. Triethyl arsenate			
6. Diarsenic pentaoxide	14. Benzyl butyl phthalate (BBP)			
7. Diarsenic trioxide	15. 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)			
8. Sodium dichromate, dihydrate	16. Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins)			